



SLOVENSKI STANDARD
SIST EN IEC 61967-8:2023

01-september-2023

Integrirana vezja - Meritve elektromagnetnega sevanja - 8. del: Merjenje sevanega oddajanja - Metoda z IC na tračnem valovodu (IEC 61967-8:2023)

Integrated circuits - Measurement of electromagnetic emissions - Part 8: Measurement of radiated emissions - IC stripline method (IEC 61967-8:2023)

Integrierte Schaltungen - Messung von elektromagnetischen Aussendungen - Teil 8: Messung der abgestrahlten Aussendungen - IC-Streifenleiterverfahren (IEC 61967-8:2023)

Circuits intégrés - Mesure des émissions électromagnétiques - Partie 8: Mesure des émissions rayonnées - Méthode de la ligne TEM à plaques (stripline) pour CI (IEC 61967-8:2023)

Ta slovenski standard je istoveten z: EN IEC 61967-8:2023

ICS:

31.200	Integrirana vezja, mikroelektronika	Integrated circuits. Microelectronics
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EUROPEAN STANDARD

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NORME EUROPÉENNE

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June 2023

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English Version

Integrated circuits - Measurement of electromagnetic emissions - Part 8: Measurement of radiated emissions - IC stripline method (IEC 61967-8:2023)

Circuits intégrés - Mesure des émissions
électromagnétiques - Partie 8: Mesure des émissions
rayonnées - Méthode de la ligne TEM à plaques (stripline)
pour circuit intégré
(IEC 61967-8:2023)

Integrierte Schaltungen - Messung von
elektromagnetischen Aussendungen - Teil 8: Messung der
abgestrahlten Aussendungen - IC-Streifenleiterverfahren
(IEC 61967-8:2023)

This European Standard was approved by CENELEC on 2023-06-07. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61967-8:2023 (E)**European foreword**

The text of document 47A/1152/FDIS, future edition 2 of IEC 61967-8, prepared by SC 47A "Integrated circuits" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61967-8:2023.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2024-03-07
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2026-06-07

This document supersedes EN 61967-8:2011 and all of its amendments and corrigenda (if any).

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This document has been prepared under a Standardization Request given to CENELEC by the European Commission and the European Free Trade Association.

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The text of the International Standard IEC 61967-8:2023 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated:

IEC 61967-2 NOTE Approved as EN 61967-2

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-131	-	International Electrotechnical Vocabulary - Part 131: Circuit theory	-	-
IEC 60050-161	-	International Electrotechnical Vocabulary. Chapter 161: Electromagnetic compatibility	-	-
IEC 61000-4-20	-	Electromagnetic compatibility (EMC) - Part 4-20: Testing and measurement techniques - Emission and immunity testing in transverse electromagnetic (TEM) waveguides	EN IEC 61000-4-20	-
IEC 61967-1	-	Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions	EN IEC 61967-1	-



IEC 61967-8

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Integrated circuits – Measurement of electromagnetic emissions –
Part 8: Measurement of radiated emissions – IC stripline method**

**Circuits intégrés – Mesure des émissions électromagnétiques –
Partie 8: Mesure des émissions rayonnées – Méthode de la ligne TEM à plaques
(stripline) pour circuit intégré**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**INTEGRATED CIRCUITS –
MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –****Part 8: Measurement of radiated emissions –
IC stripline method**

FOREWORD

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IEC 61967-8 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

This second edition cancels and replaces the first edition published in 2011. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) frequency range of 150 kHz to 3 GHz was deleted from the scope;
- b) extension of upper usable frequency to 6 GHz or higher as long as the defined requirements are fulfilled.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47A/1152/FDIS	47A/1153/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts of the IEC 61967 series, under the general title *Integrated circuits – Measurement of electromagnetic emissions* can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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